

Catalytic CVD of Graphene on Graphite and Resist-Free Method for Multi- Electrodes Devices



C. Soldano^{1,2}, I. Kholmanov¹, E. Dujardin², G. Faglia¹, G. Sberveglieri¹

¹ SENSOR CNR-IDASC & Università di Brescia, Brescia (IT)

² CEMES, *Centre d'Elaboration et d'Etudes Structurales*, CNRS Toulouse (FR)

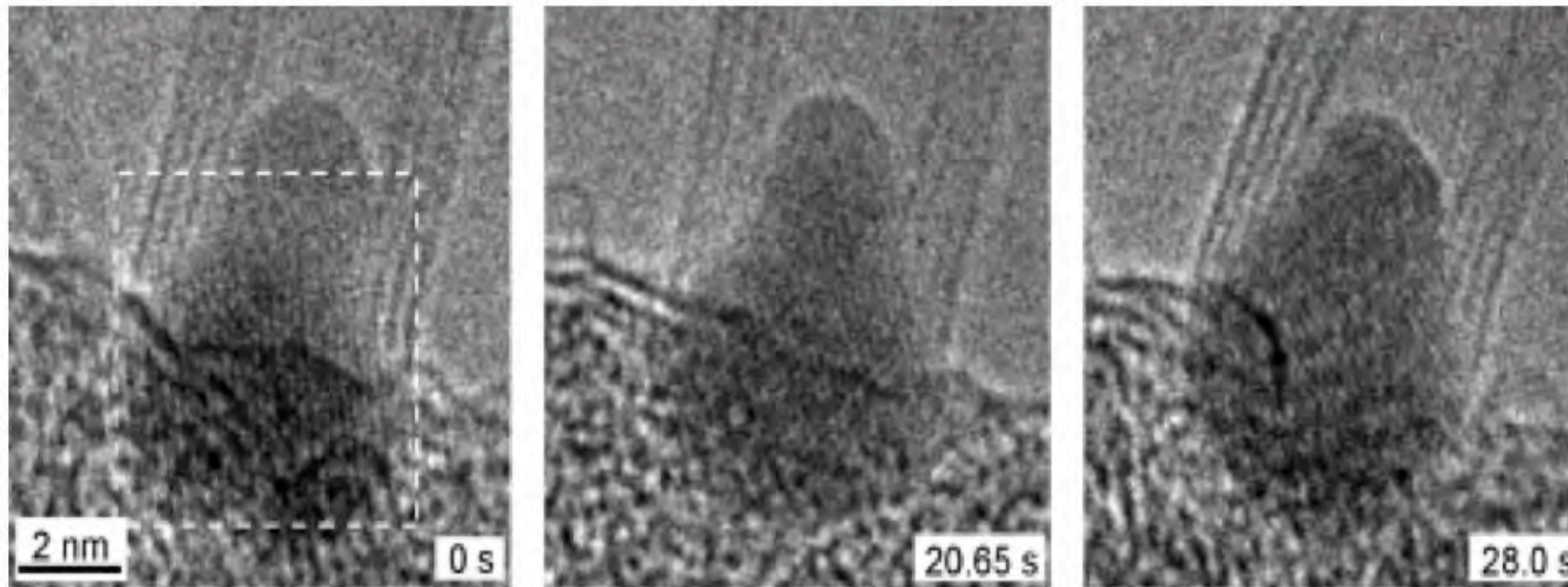
Catalytic Growth of C-Nanostructures

- Metal nanoparticles (NPs) on HOPG
- Chemical Vapor Deposition (CVD) on HOPG
- Scanning Tunneling Microscopy (STM) of C-structures

Graphene Device Fabrication

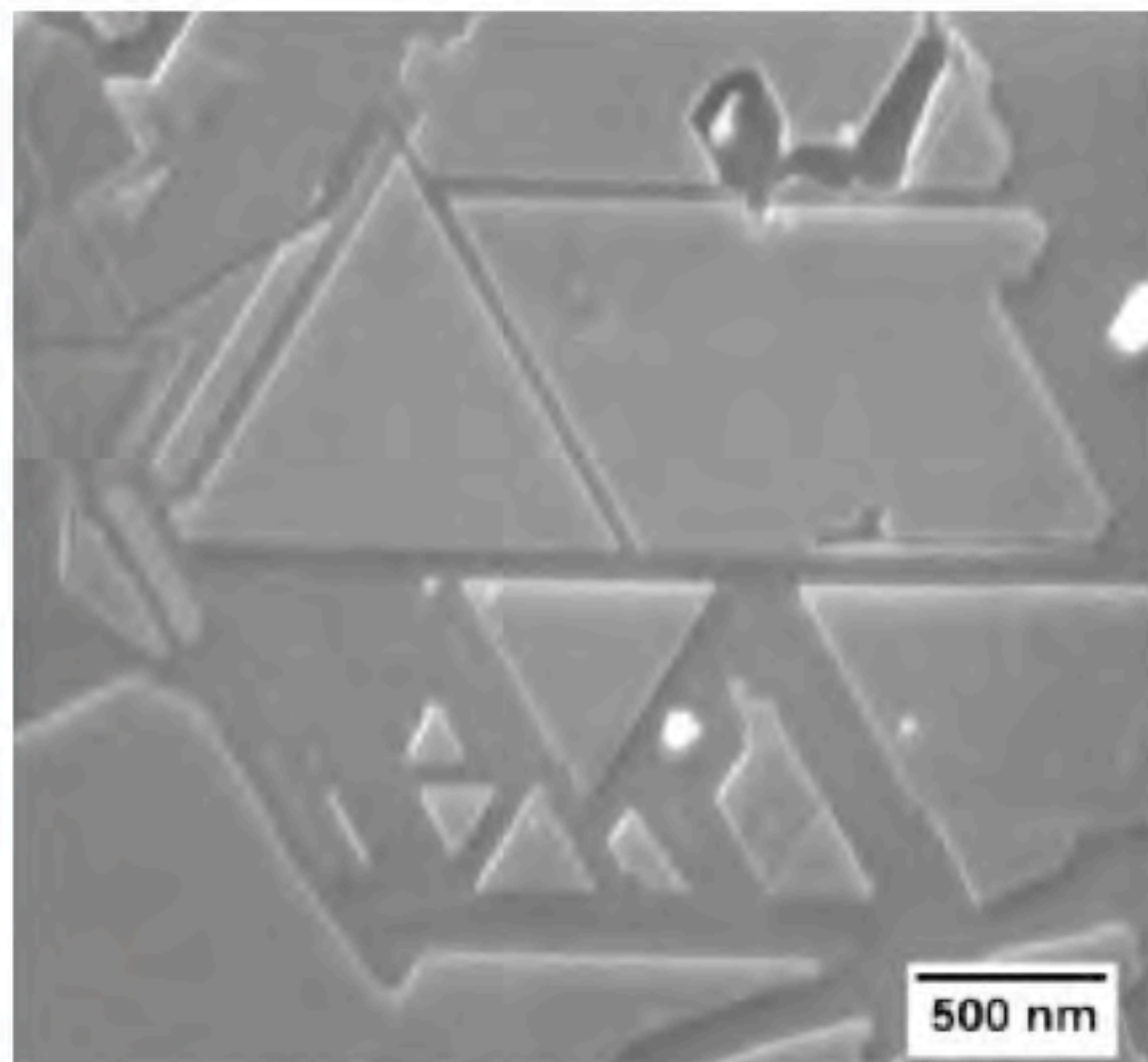
- Direct-masking technique
- Graphene/graphene-like device fabrication
- Characterization of the charge transport

Nanoparticles (NPs) to Structure Graphene

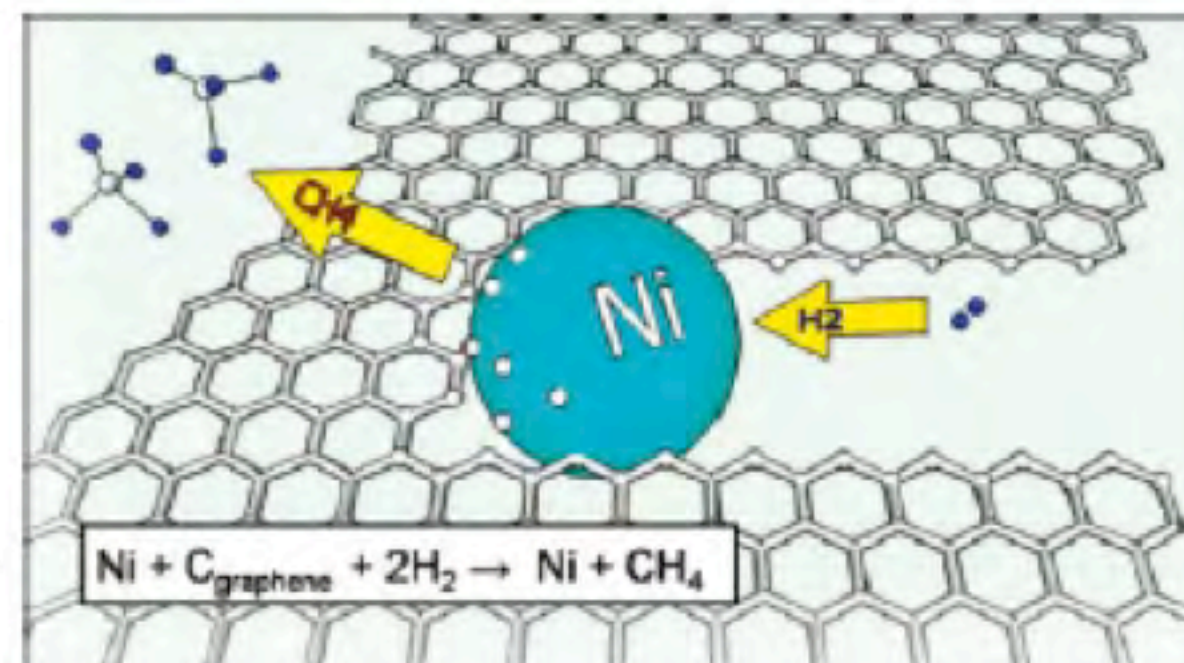


Catalytic Growth
of
Nanostructures

Yoshida *et al.* Nano Lett. **9**, 3810 (2009)



Ci *et al.*, Adv. Mater. **21**, 1 (2009)

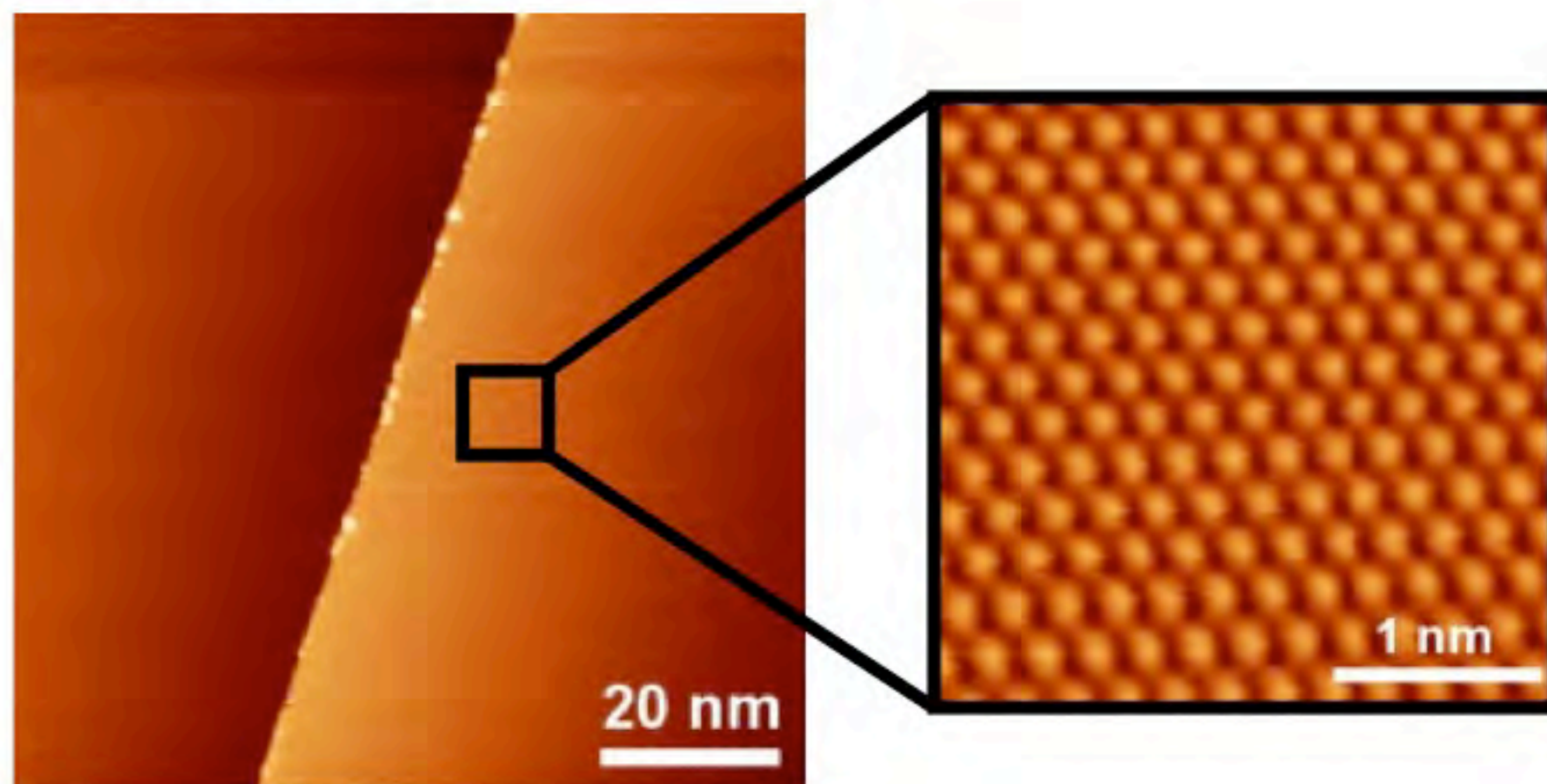


Campos *et al.* Nano Lett. **9** 2600 (2009)

Etching of
Carbon-based
Nanostructures

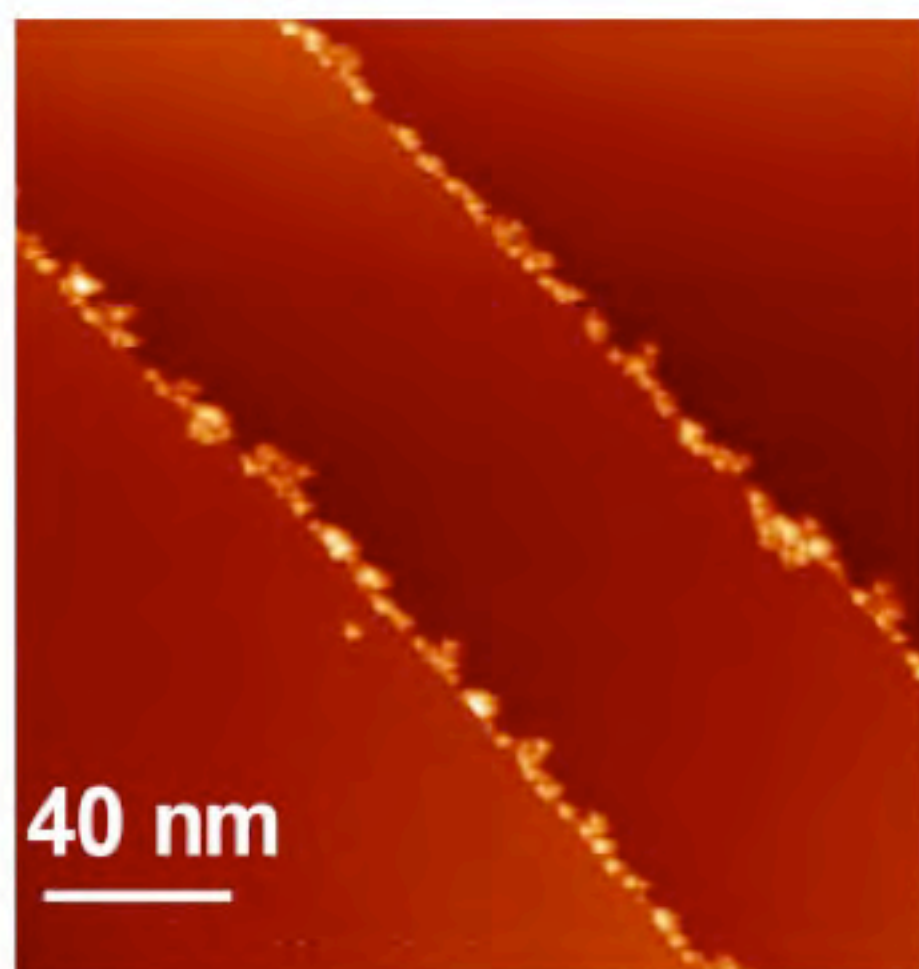
Highly Oriented Pyrolytic Graphite (HOPG)

Cleaved HOPG

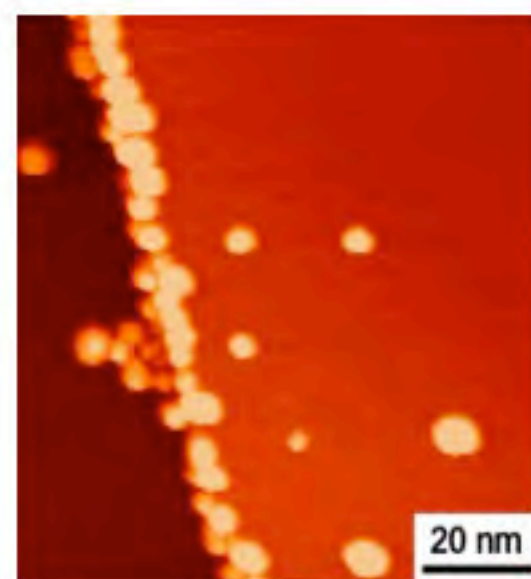


Atomically flat planes with step edges
(degassing @ 900°C after cleavage)

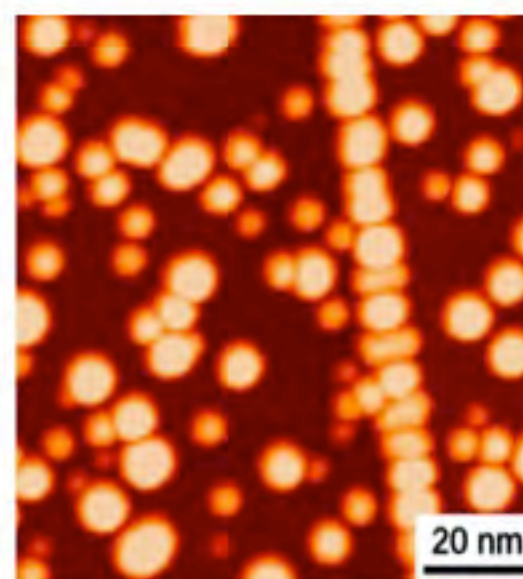
Fe deposition (<1ML)



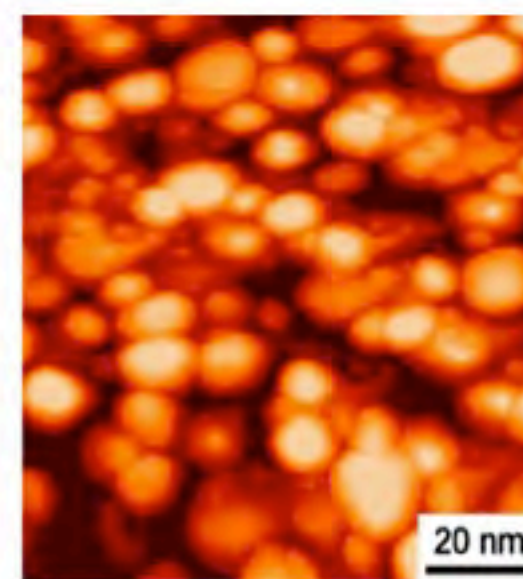
e-beam sublimation at room temperature



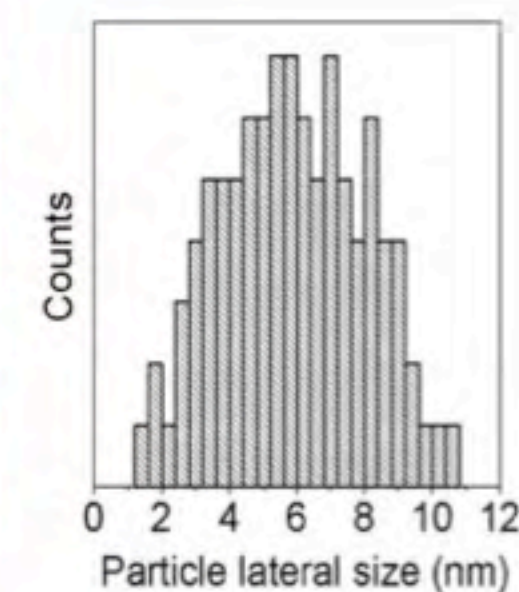
0.3 ML



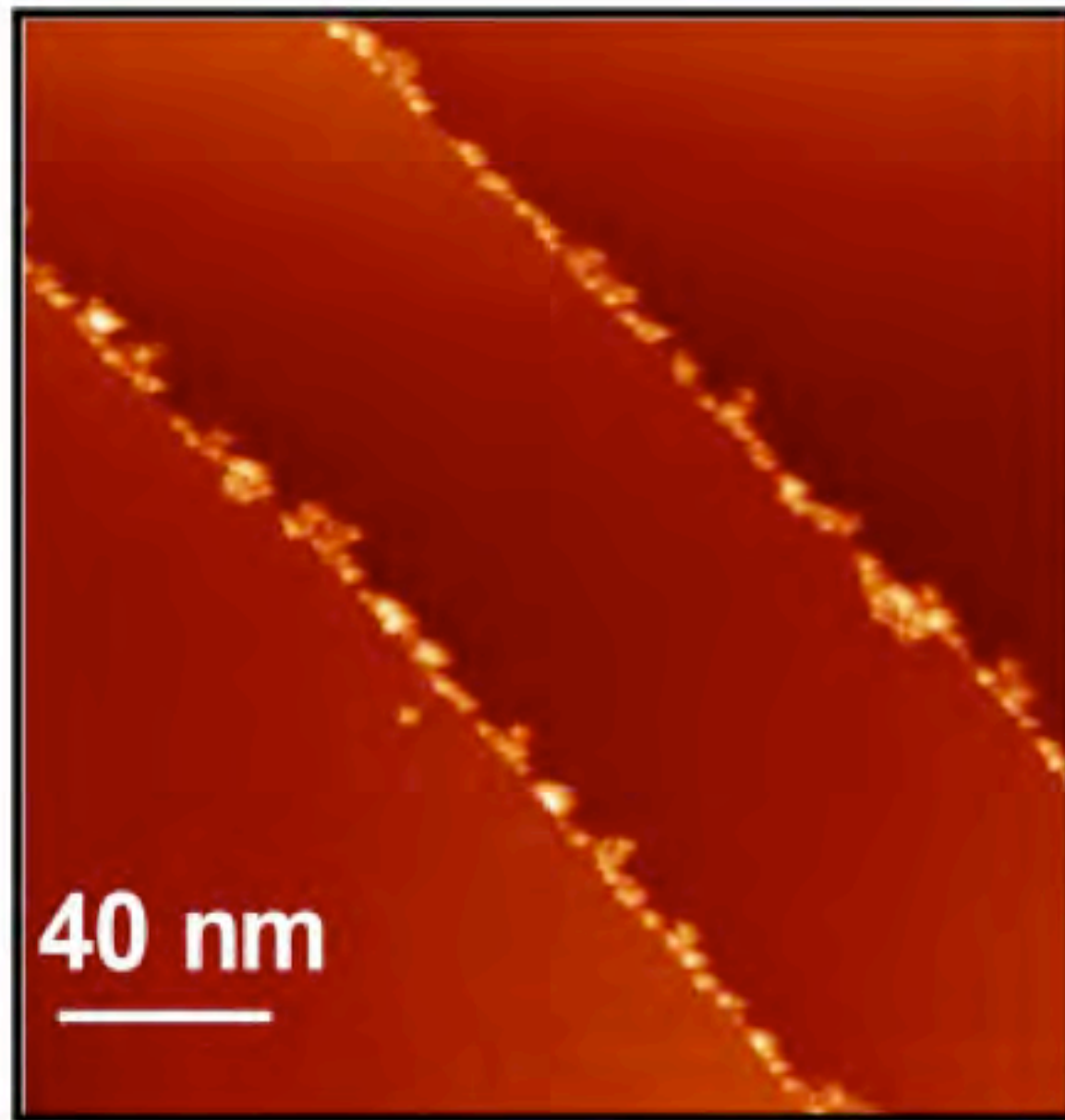
2 ML*



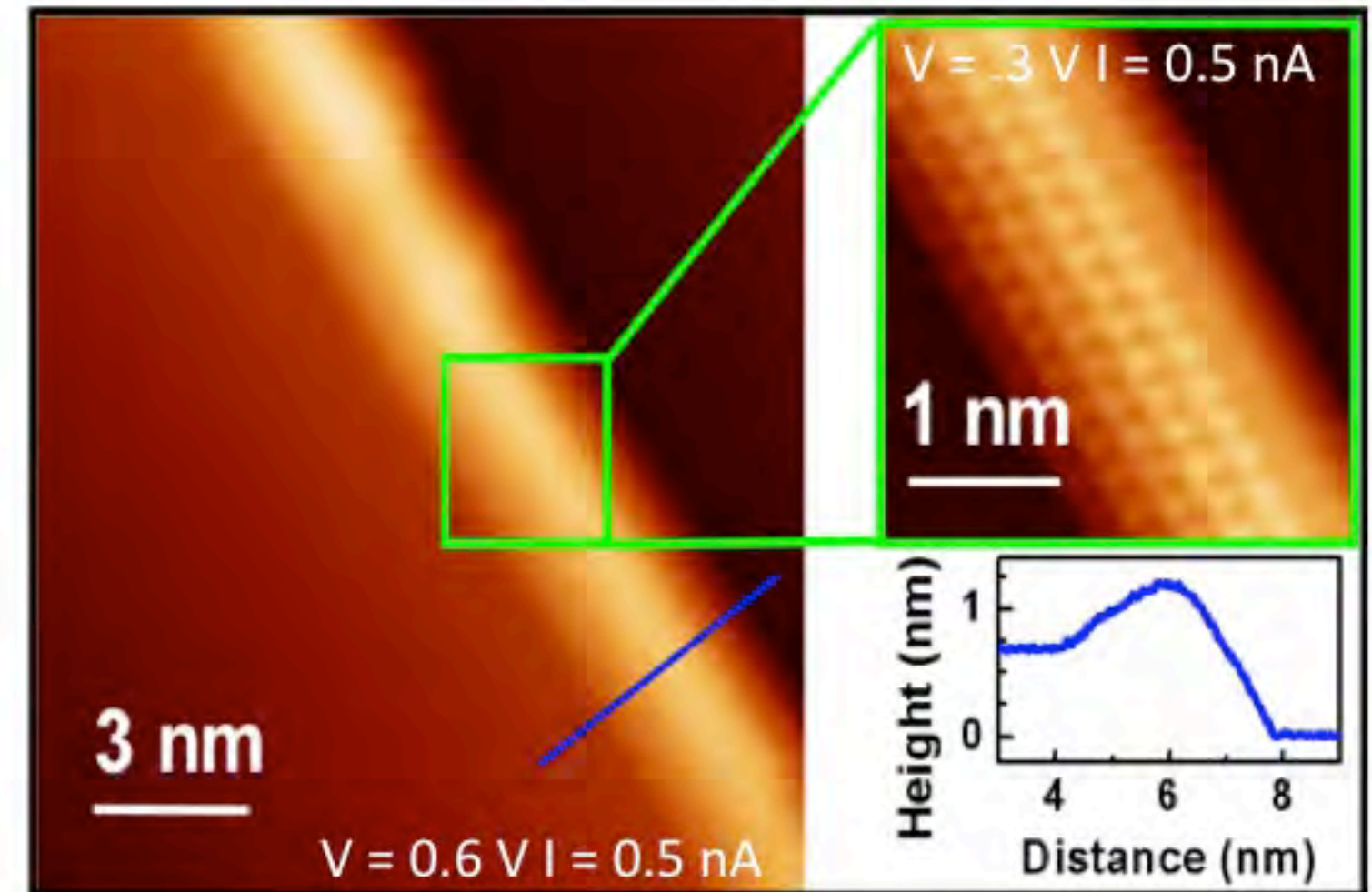
6 ML



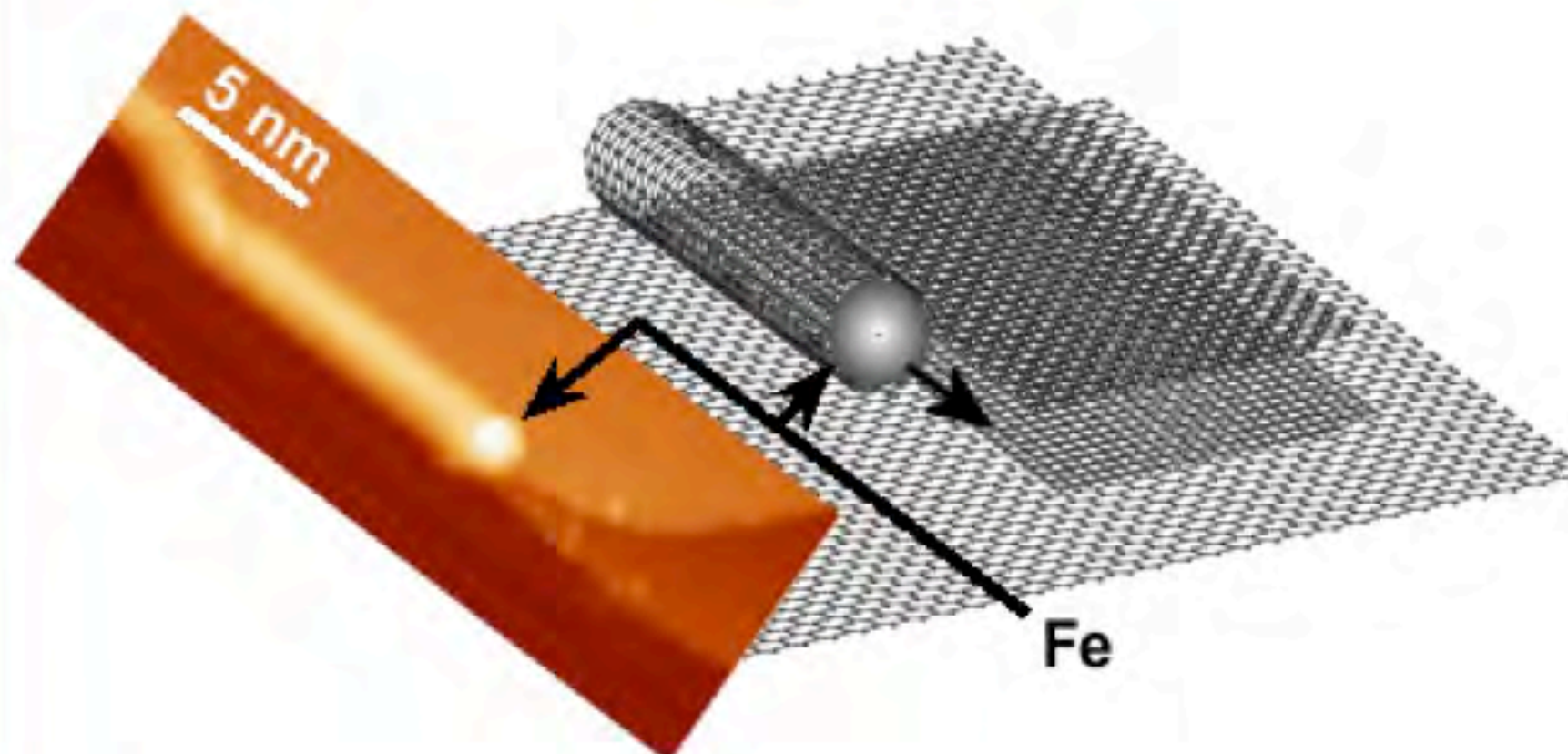
Growth of Curved Graphene Sheets (CGS) – Fe <1ML



CH_4 @ 900°C
 $p=2 \times 10^{-4} \text{ mbar}$



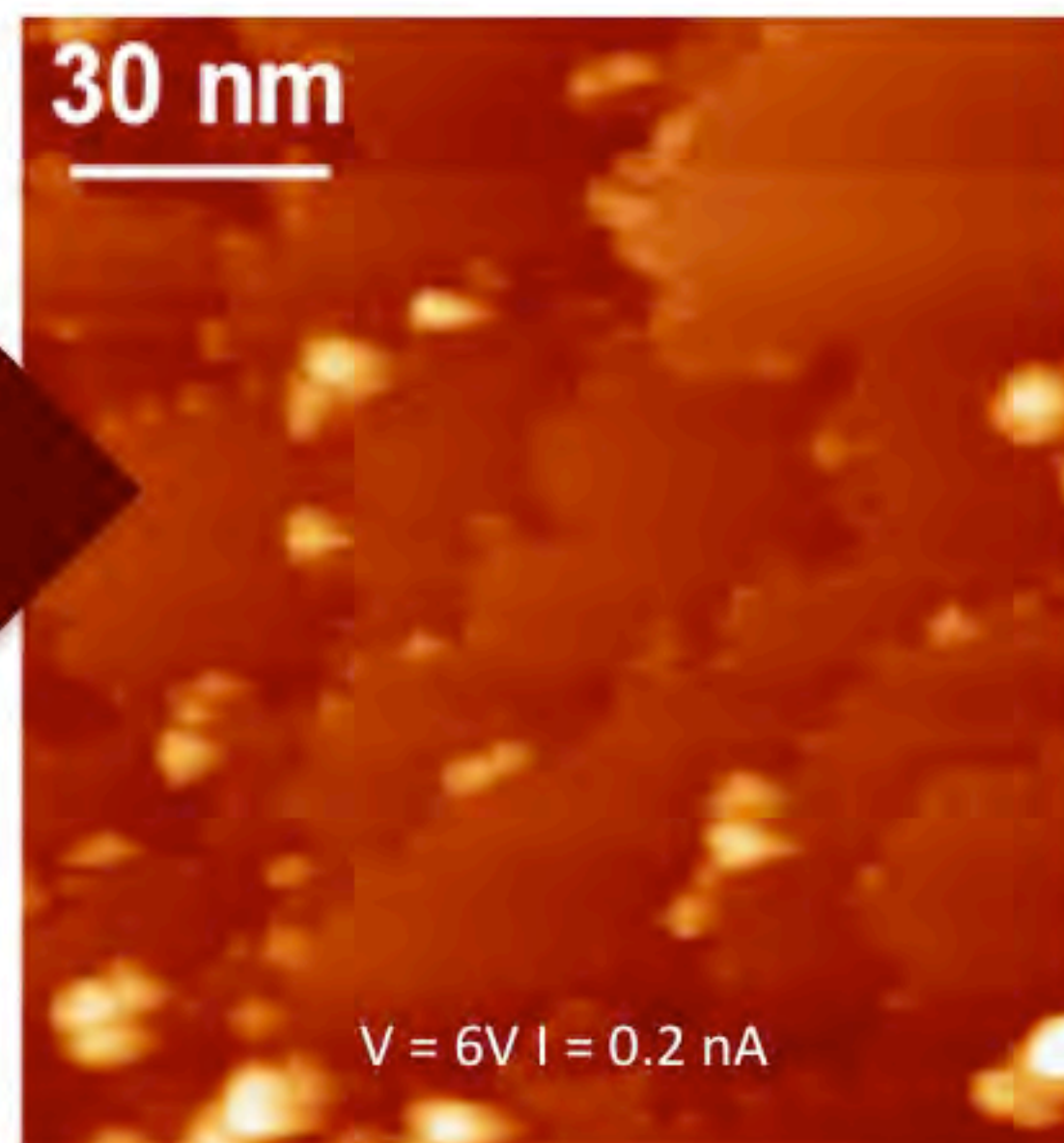
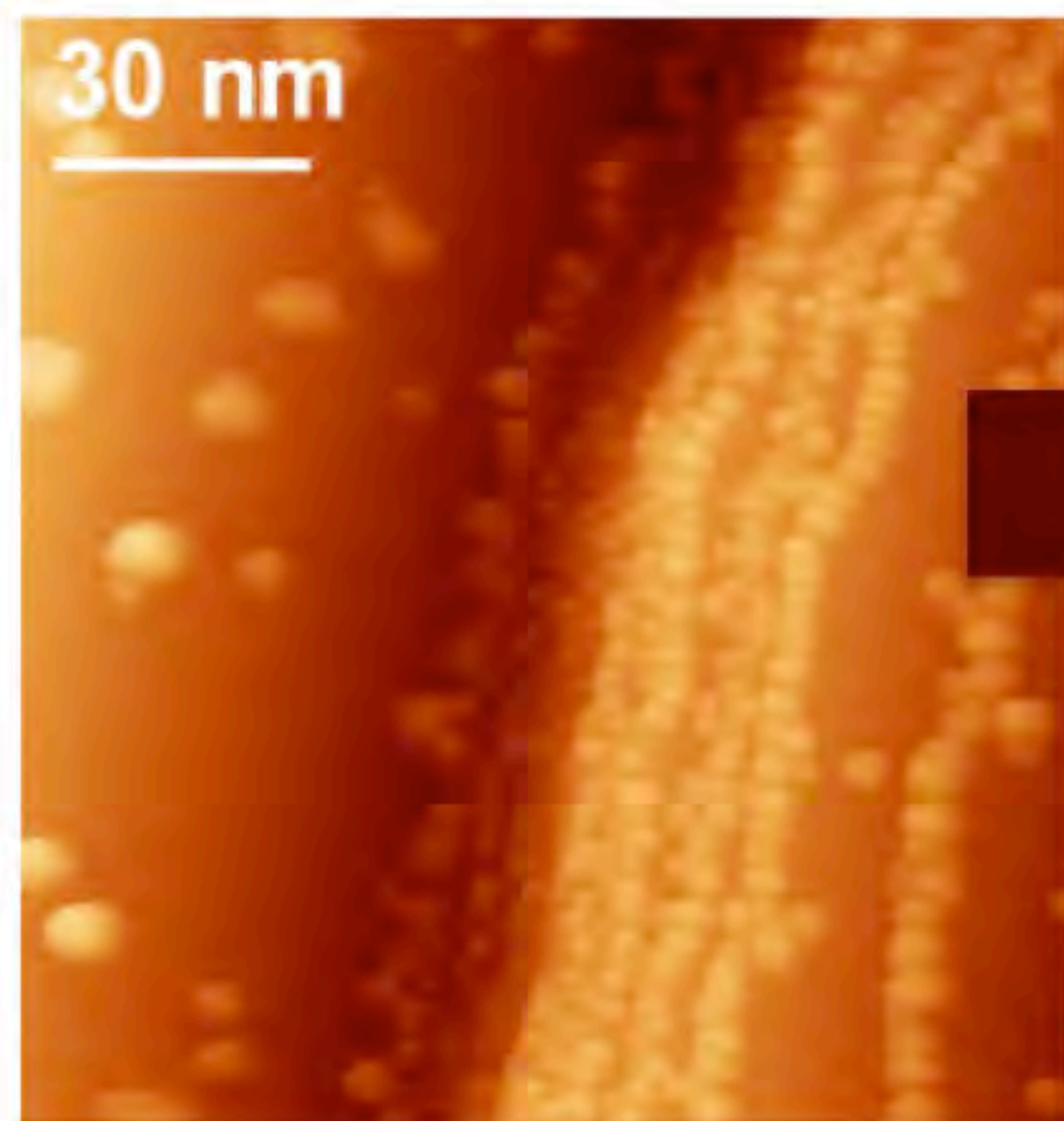
1. abrupt edges $\rightarrow$ continuously smooth curved graphene sheet (CGS)
2. structures similar to CNT (no Fe)



CH_4 decomposition at the edge C-atoms and creation of chemical bonds

C-atoms can meet both edges leading to the growth of CGS (*zipper-like mechanism*).

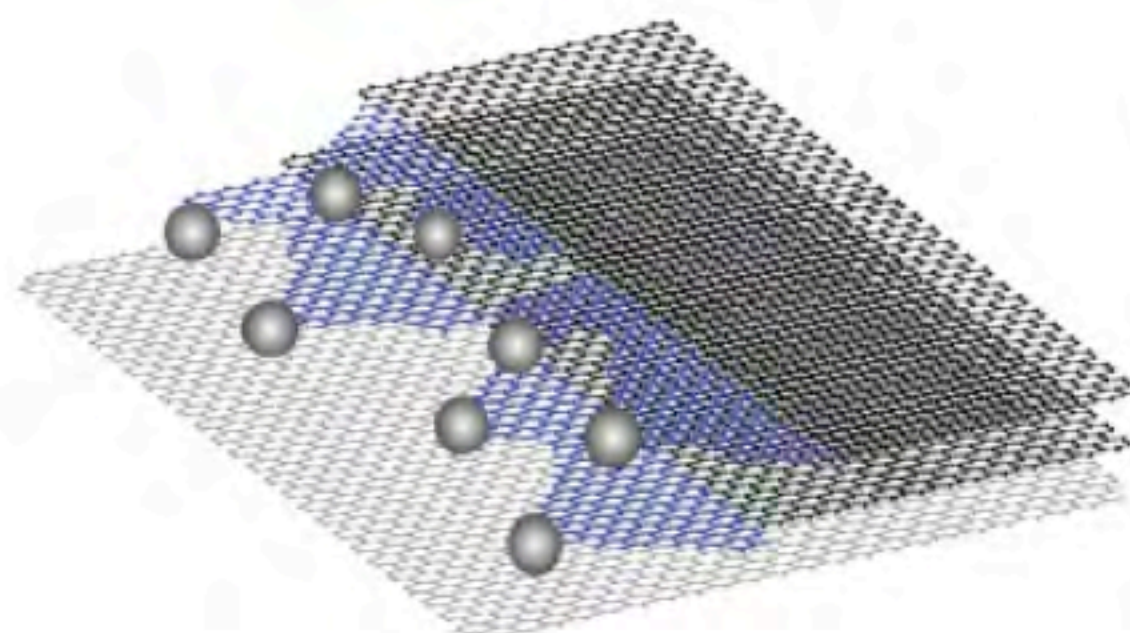
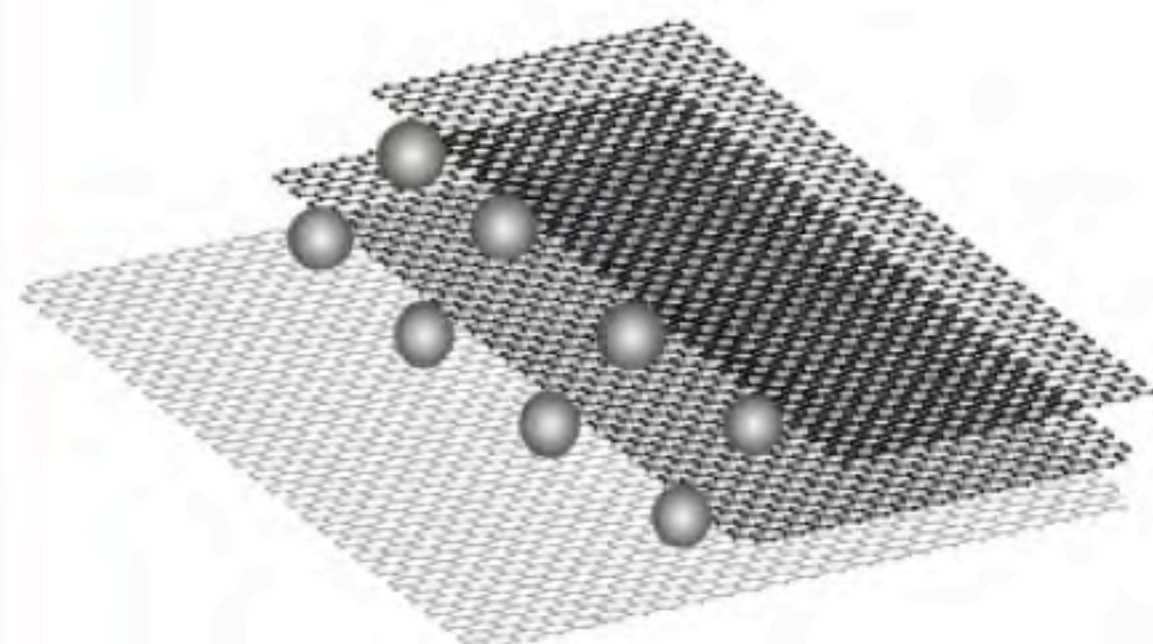
Growth Along the Edges – Fe <1ML



d with Fe nanoparticles (nom
ges after the CVD process, d
[inset: calibrated line profile
mage of HOPG step edges co
nA). Inset: calibrated line pr
nces to colour in this figure]

Reference (no Fe)

irregular edges, large terraces



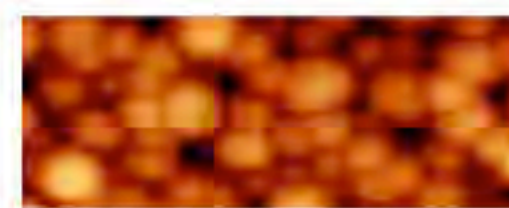
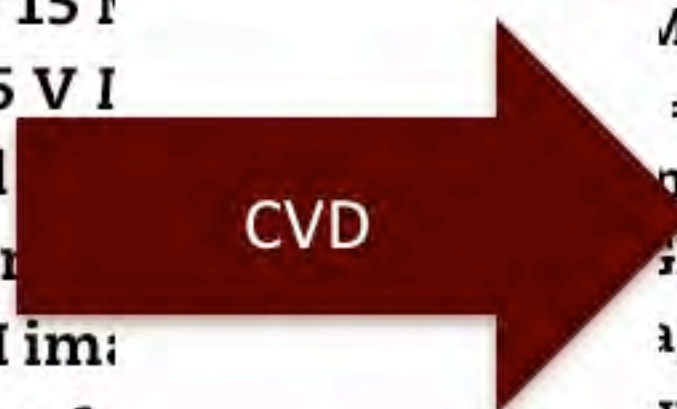
grown graphene is not
distinguishable from original terrace
(no crystallographic difference)

role of defect for the shape

Graphene Island Growth – Fe > 15ML



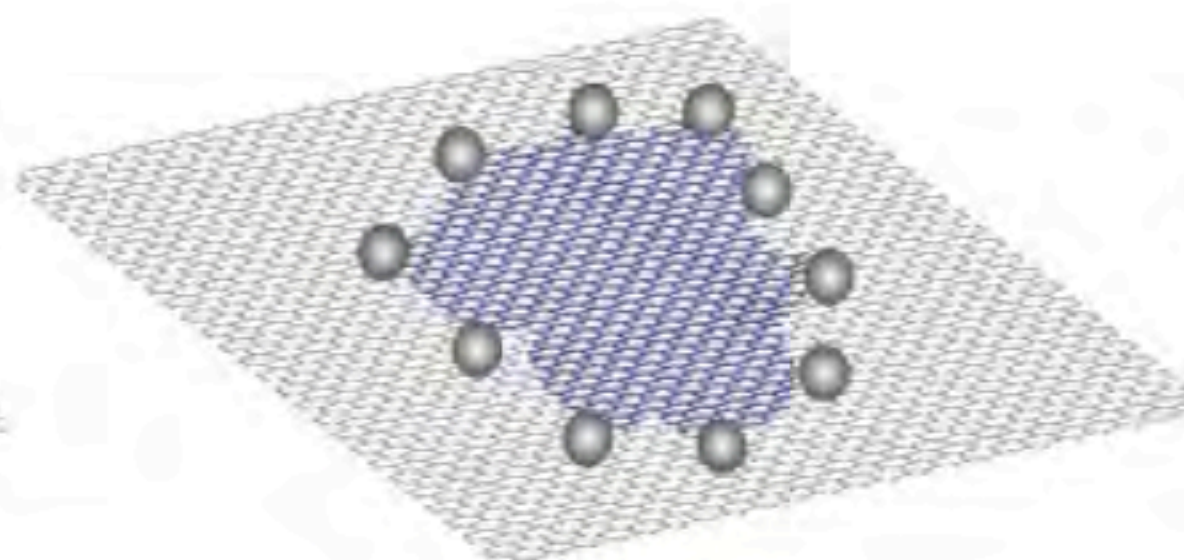
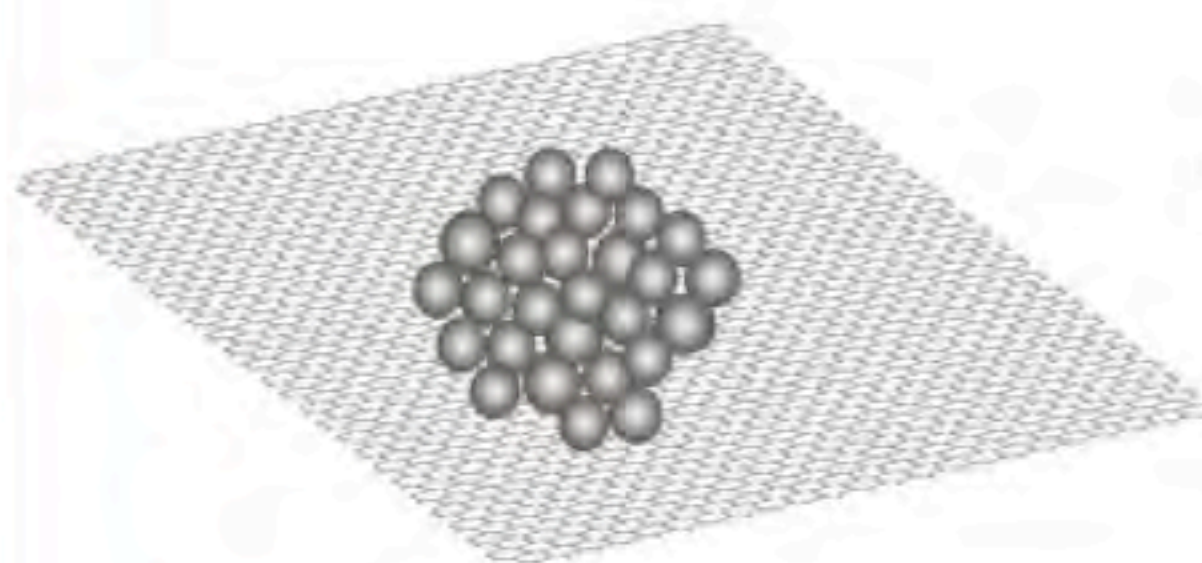
Fig. 3 – (a) STM image of 15 ML Fe film before CVD process ($V = -2.5$ V $I = 0.2$ nA). (b) STM images of PGI grown on the terraces of the (0 0 0) metal particles after the CVD reaction ($V = -2.5$ V $I = 0.6$ nA). The circular white arrow indicates the grown second graphene layer. The blue line indicates a calibrated scale bar. (For interpretation of the references to colour in this figure legend, the reader is referred to the web version of this article.)



ML Fe film forming 3D nanoparticles and homogeneously covering the surface ($V = -2.5$ V $I = 0.2$ nA). (b) STM images of PGI grown on the terraces of the (0 0 0) metal particles after the CVD reaction ($V = -2.5$ V $I = 0.6$ nA). The circular white arrow indicates the grown second graphene layer. The blue line indicates a calibrated scale bar. (For interpretation of the references to colour in this figure legend, the reader is referred to the web version of this article.)

Heig
Carbon 48,1619 (2010)
Kholmanov et al.

large number of isolated graphene islands
(tens of nms)

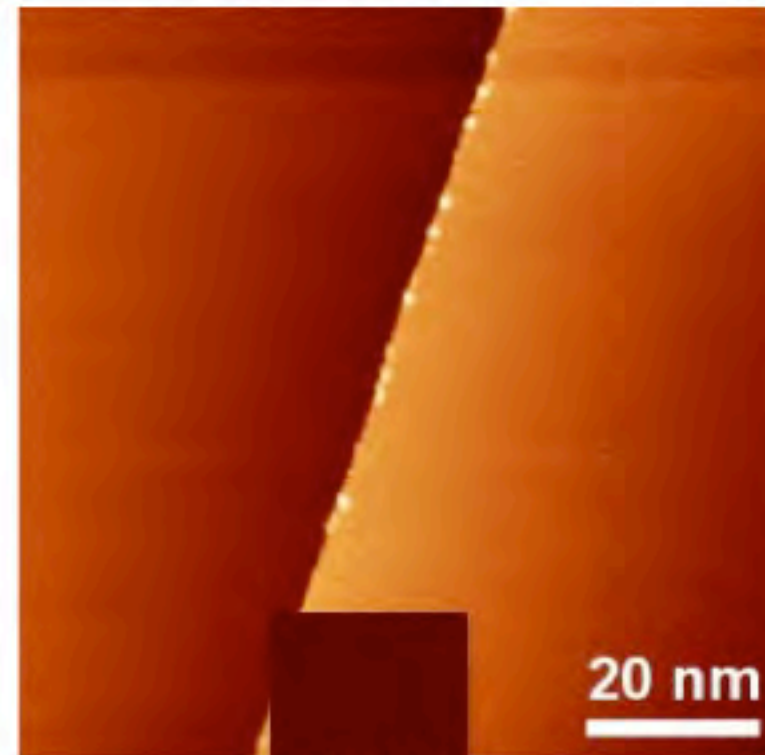


Fe evaporation vs. CH_4 decomposition

Possible role of defect for the shape

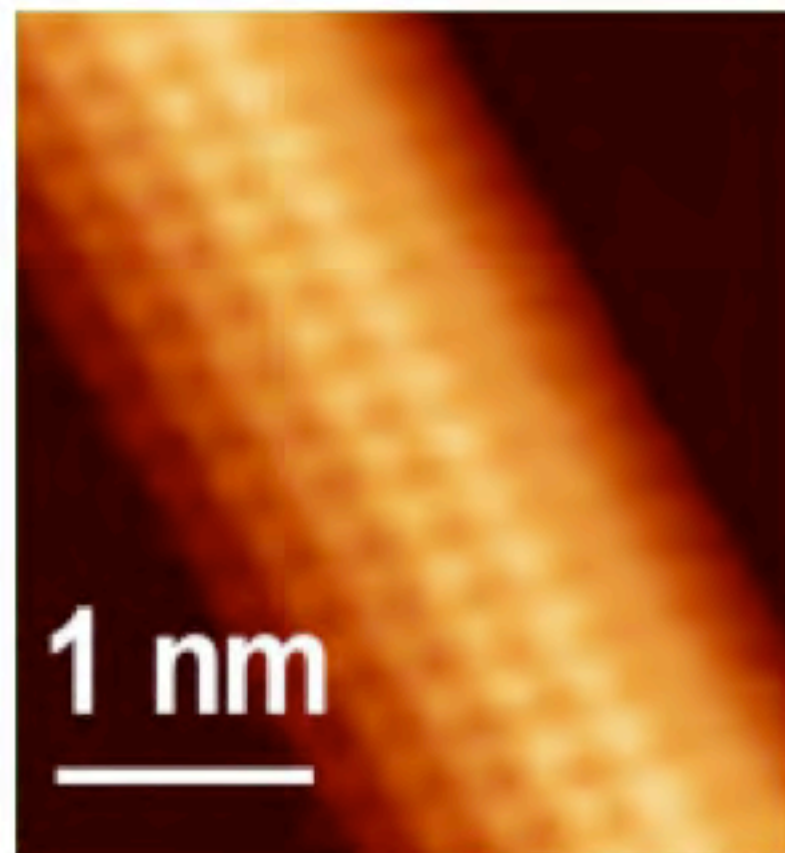
I. Conclusion

Cleaved HOPG

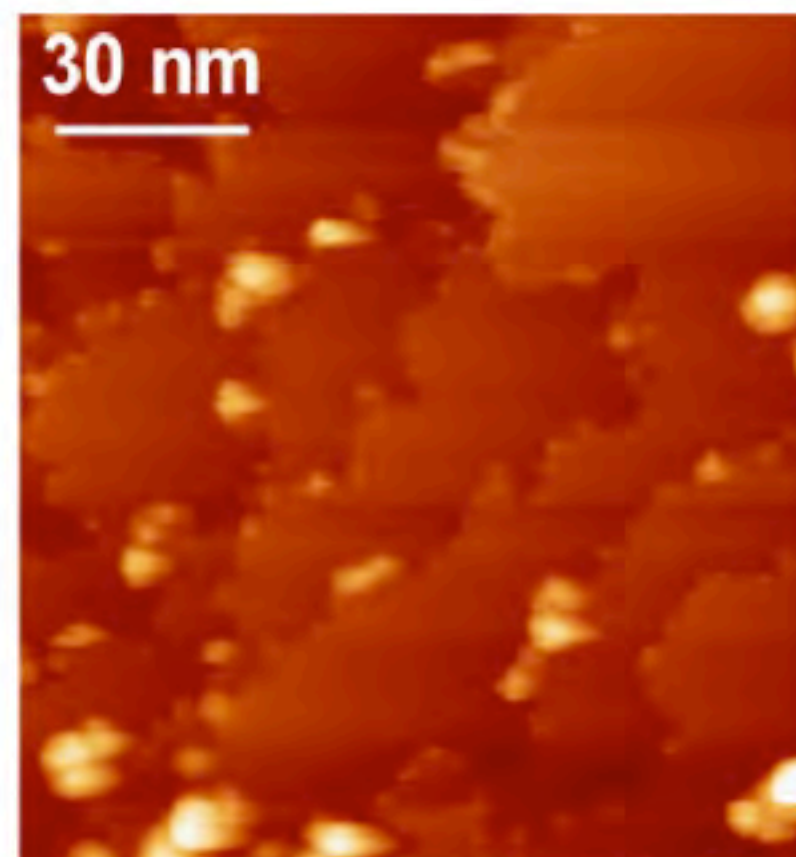


CVD

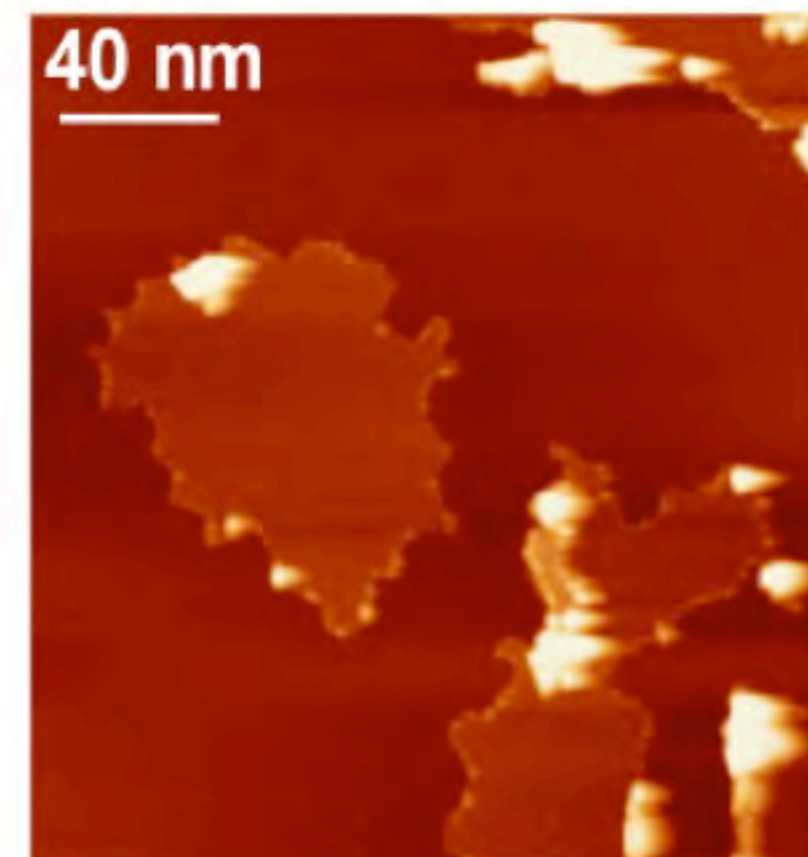
Carbon Nanostructures



Tubular (CNT-like)



Terraces



Islands

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Graphene Device Fabrication

- Direct-masking technique
- Graphene/graphene-like device fabrication
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Device Fabrication : Going *Ion-* and *Resist-free*

Device fabrication:

Conventional techniques to fabricate graphene-based-devices:

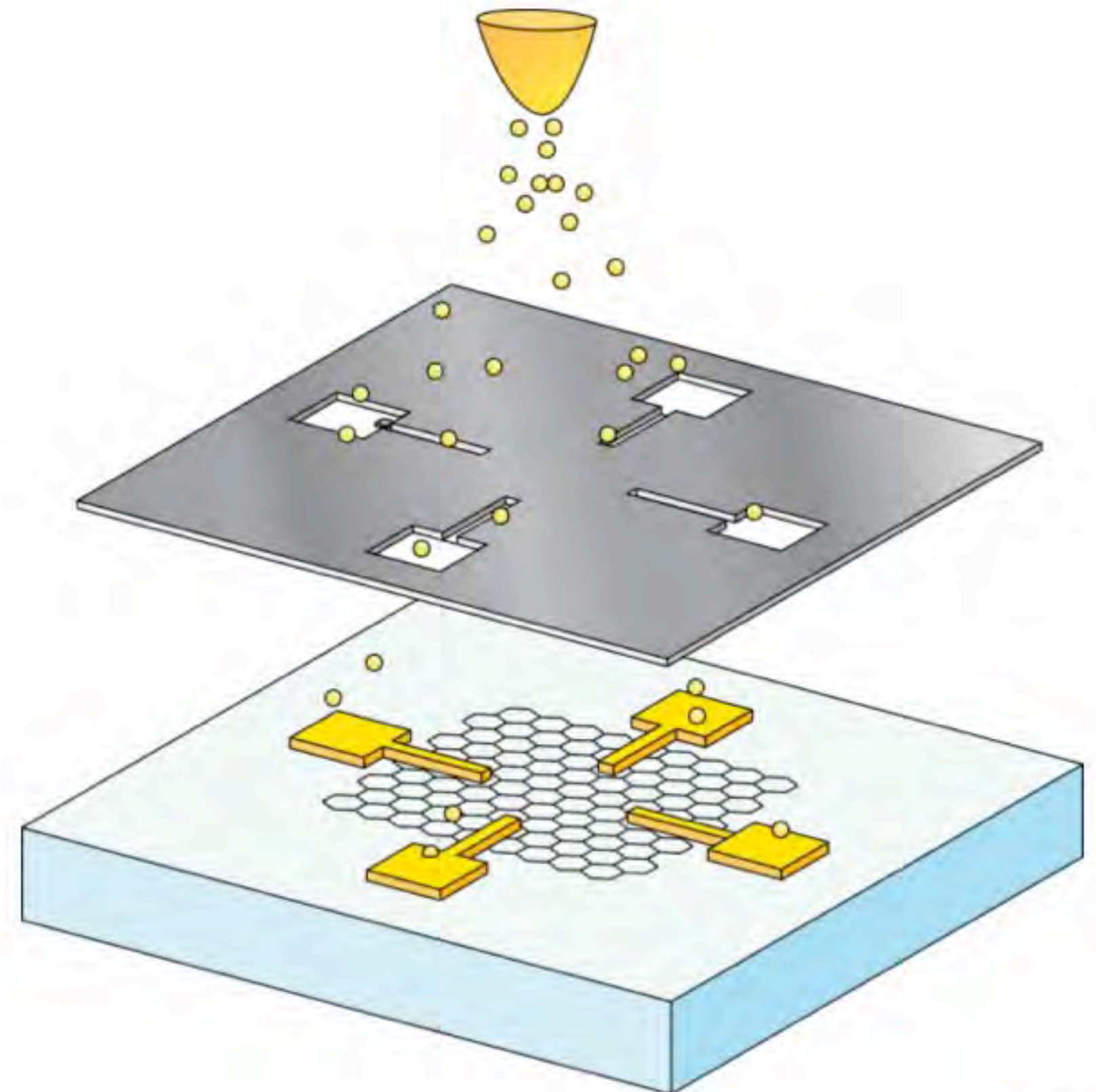
e-beam lithography (photo-resist residues, lift-off)
FIB lithography (ion implantation, amorphization)
others...



**post-fabrication treatments to recover
intrinsic properties**

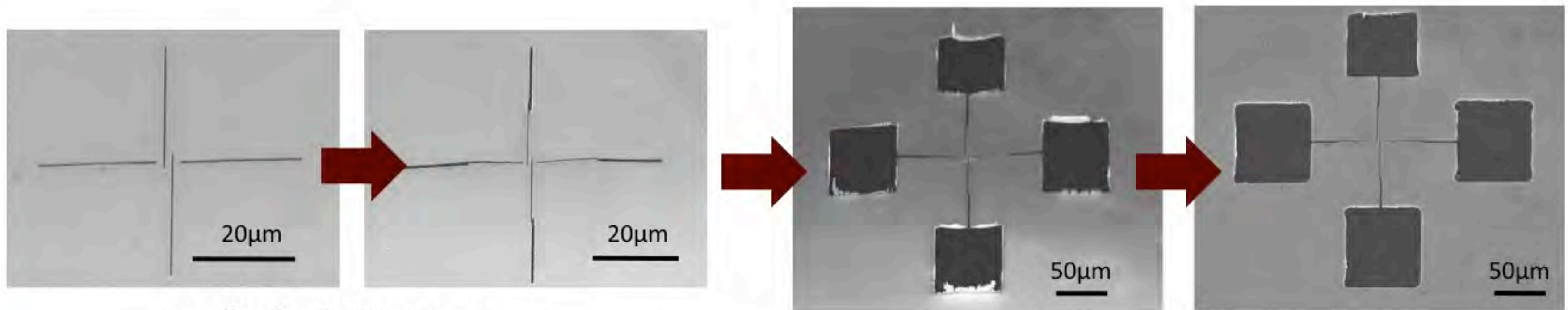
Direct masking on
graphene/graphene-like material

- the technique;
- membrane fabrication and alignment;
- study of the charge transport;



Membrane Fabrication

Patterns are fabricated on Si_3N_4 membranes ($\sim 250\text{nm}$ thickness) by XeF_2 -assisted ion-beam etching (FIB) lithography. FIB offers great versatility in the pattern shape.



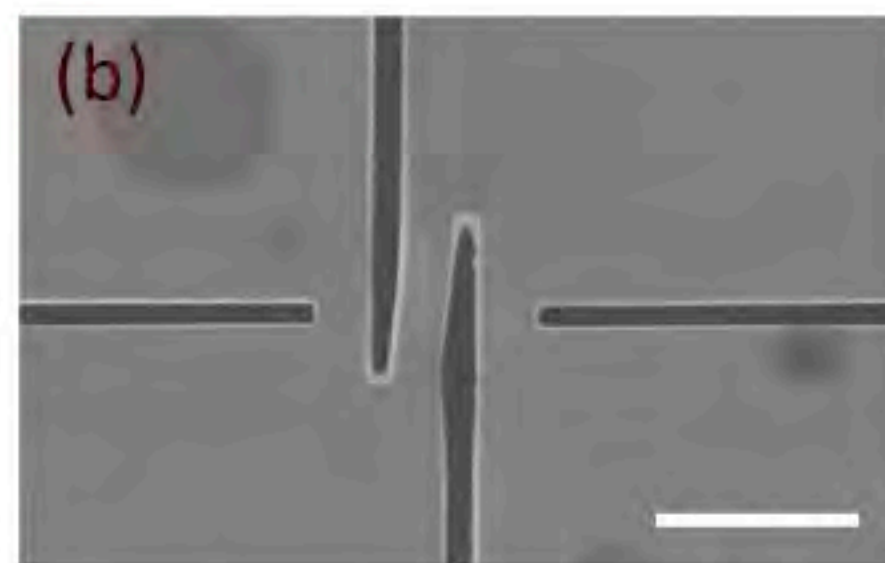
smaller leads ($10 \times 0.1\mu\text{m}$)
→ small FIB currents ($\sim 10\text{s pA}$)

larger electrodes ($50 \times 50\mu\text{m}$)
→ large FIB currents ($\sim \text{nA}$)

fine polishing



Hall bar



4-pr interdigitated

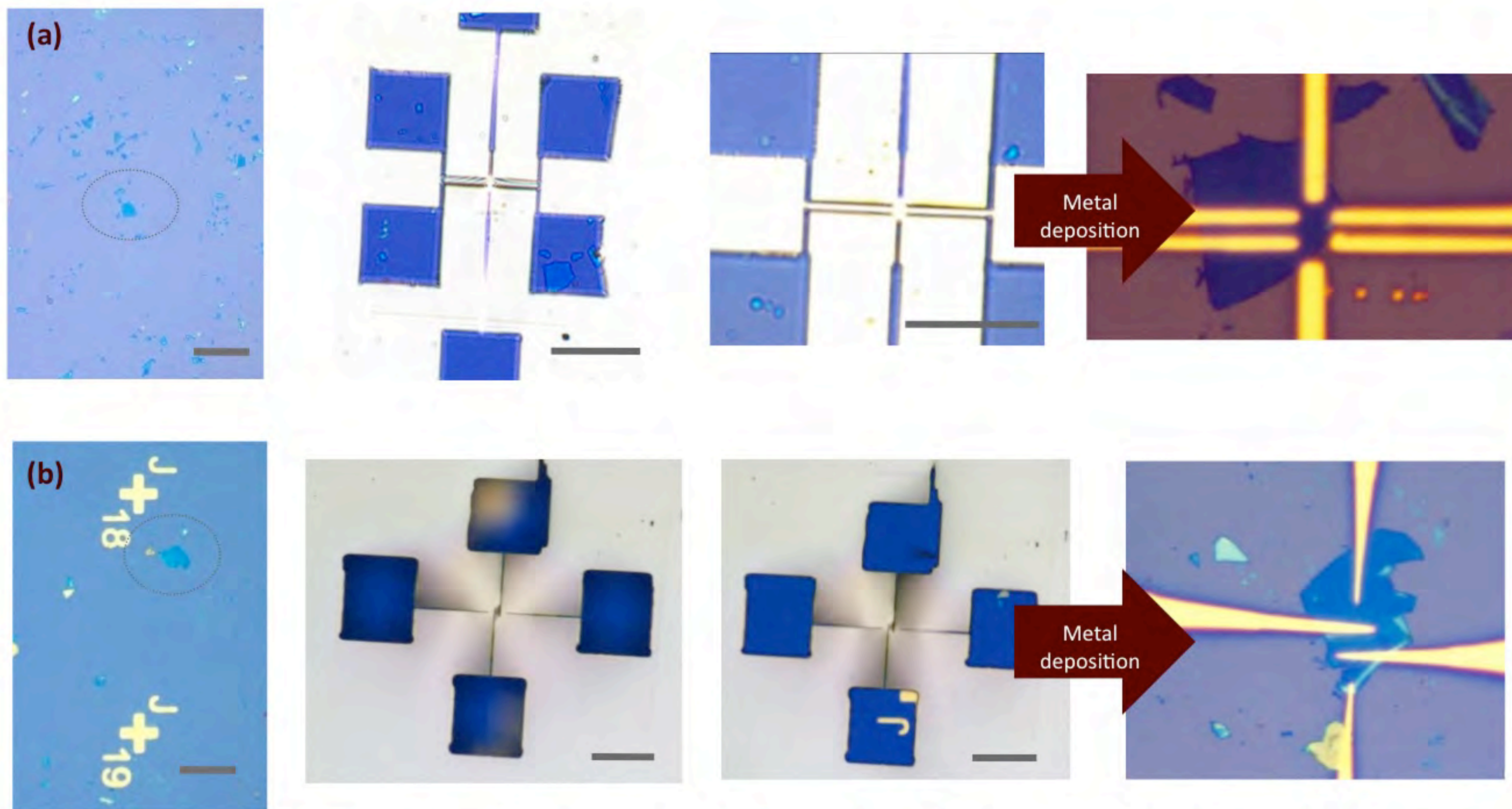


Van der Pauw

(Scale bar is $10\mu\text{m}$)

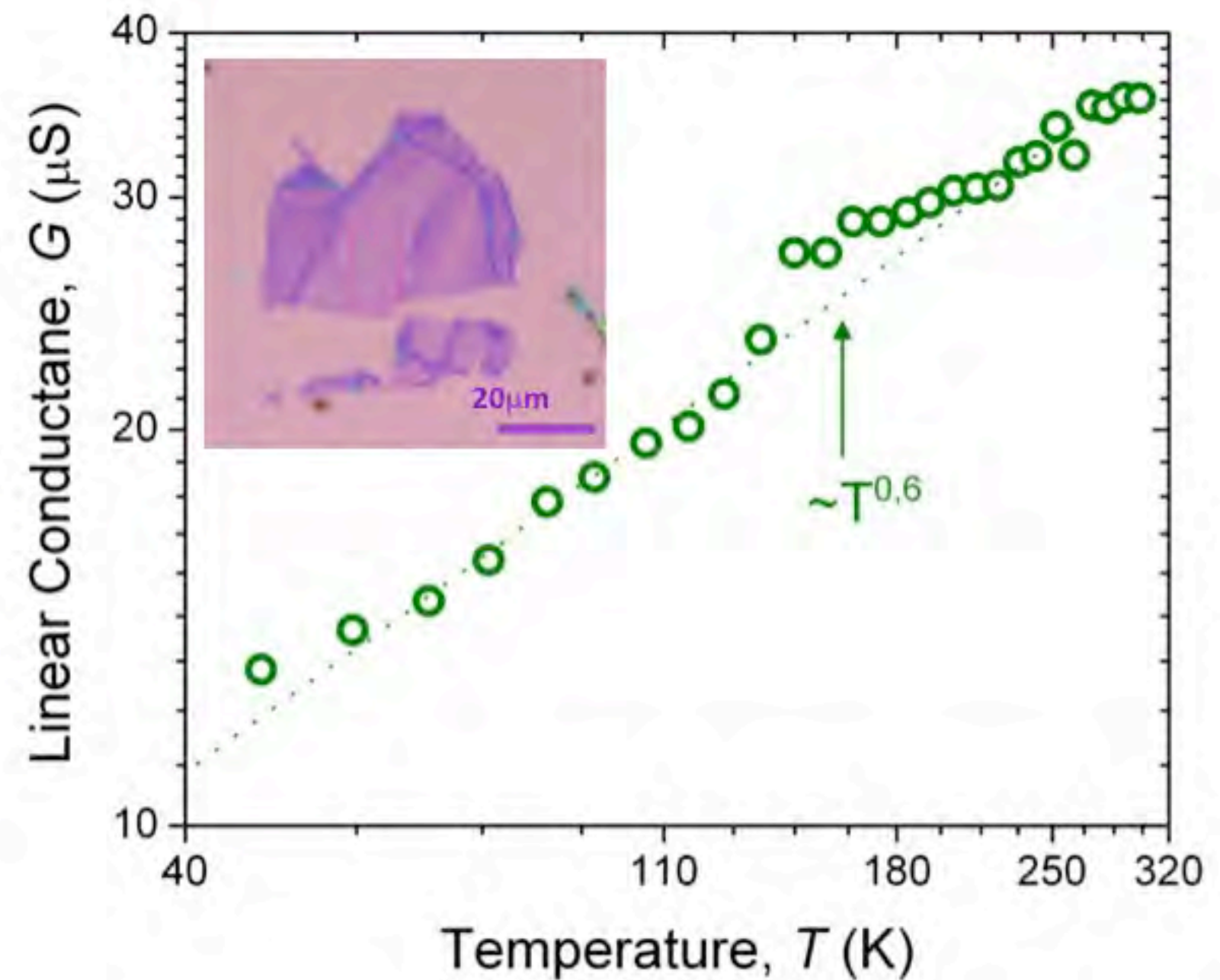
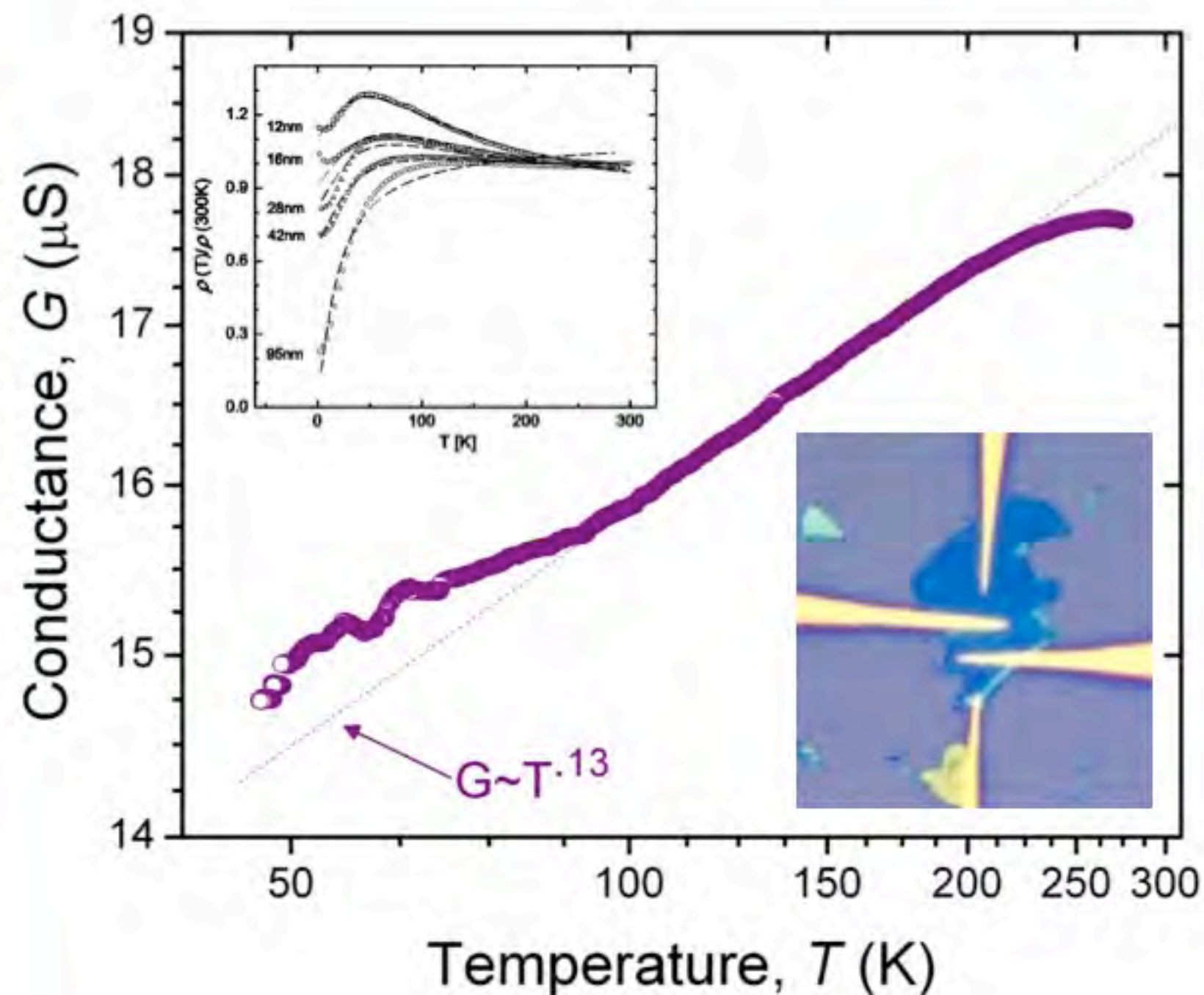
Membrane Alignment

In collaboration with Dr. Grisolia, INSA, Toulouse



Reference marks facilitate sample location and alignment process. Scale bar is 50 μ m.

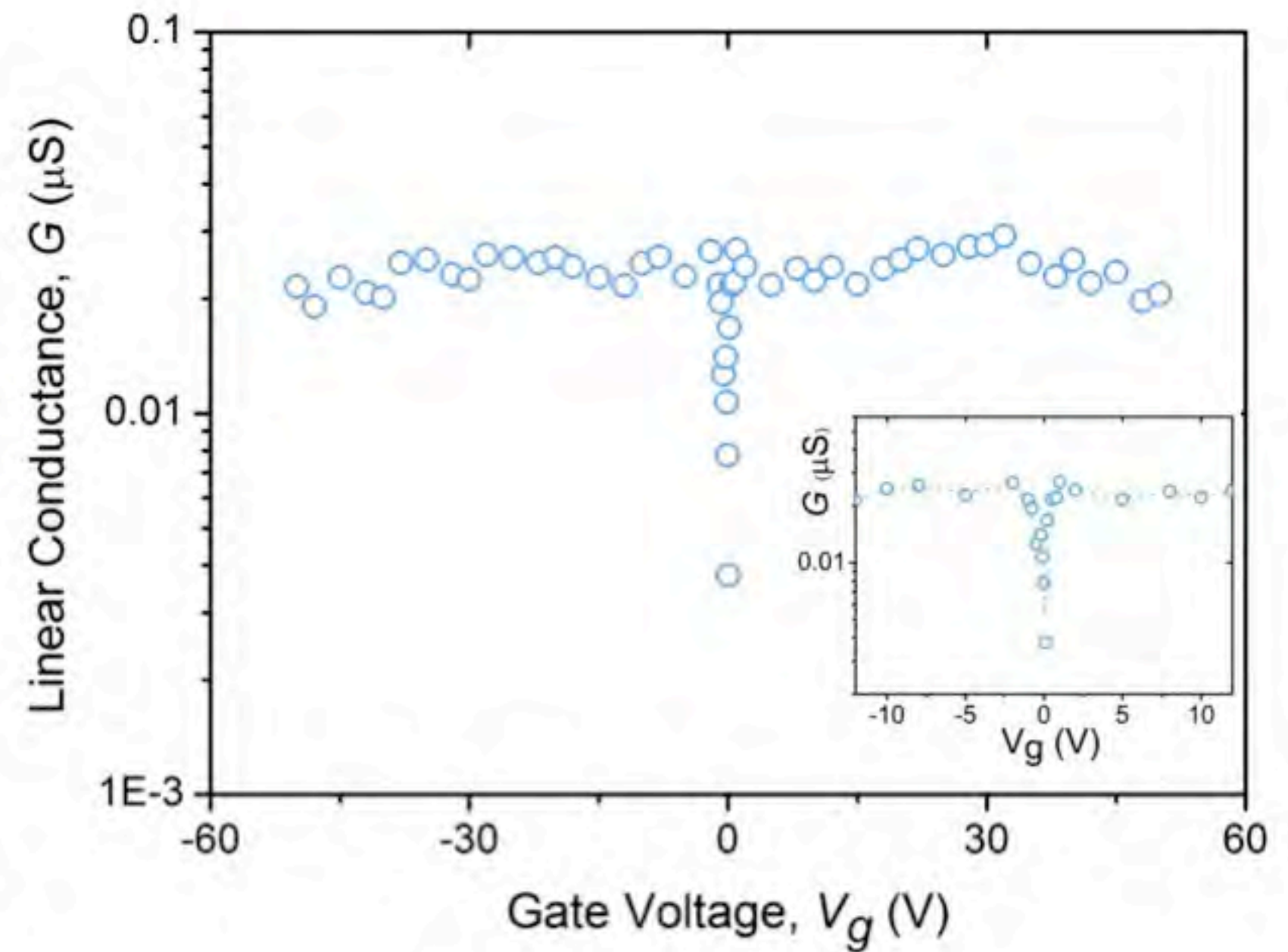
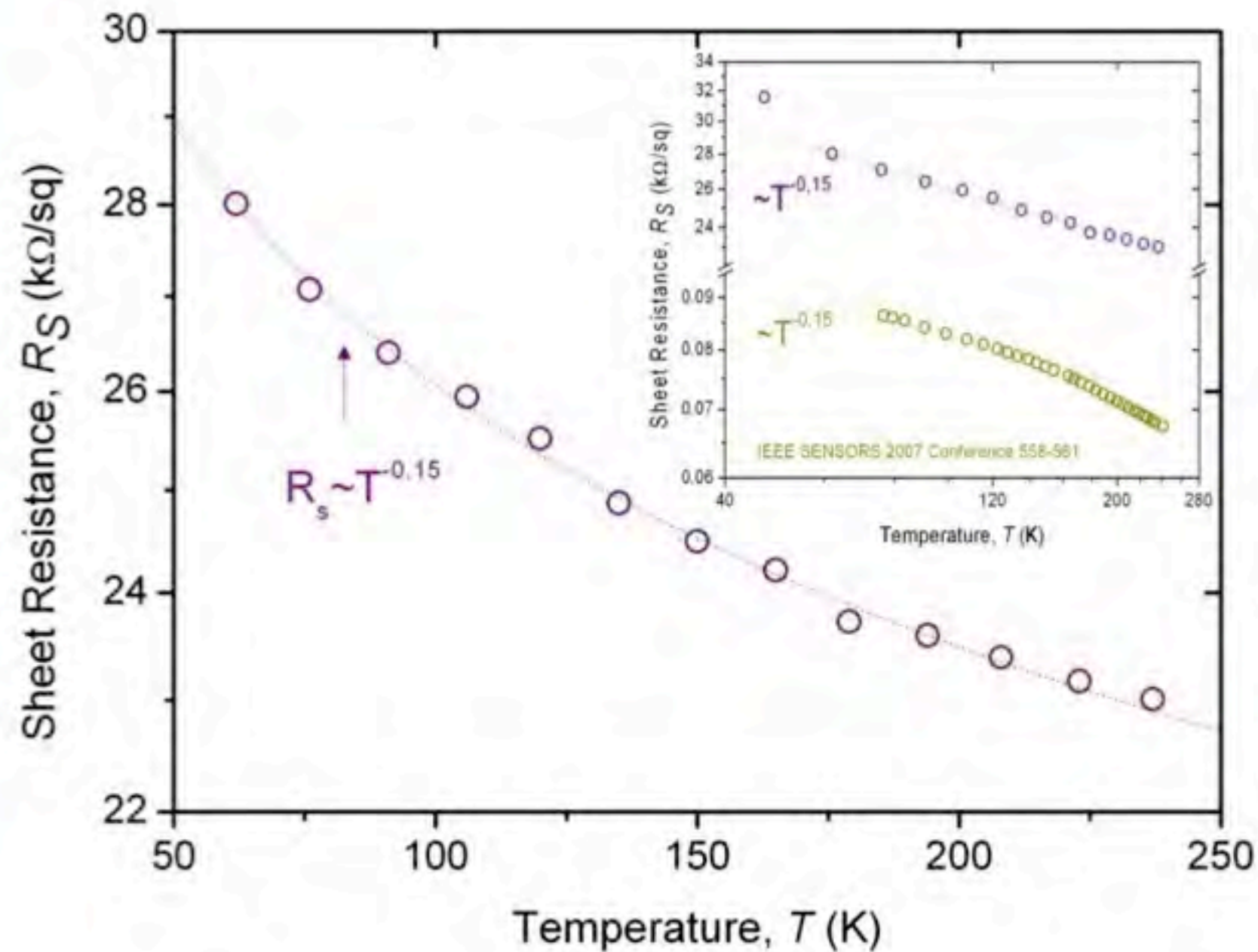
Multielectrodes Device I: Conductance



(Left) Temperature dependence of the conductance, G vs. T of an FLG (9nm) device. (Inset) Normalized resistivity as function of temperature for various thicknesses graphitic devices [APL **86**, 073104 (2005)].

(Right) Temperature dependence of the conductance for a bi-layer device.

Multielectrodes Devices II: Sheet Resistance and Gate Voltage



(Left) Temperature dependence of the sheet resistance of bi-layer sample. Experimental data are consistent with the literature [IEEE SENSORS 2007 Conference 558].

(Right) Low-temperature gate-modulated charge transport (~ 42 K). The small dip suggests the presence of the Dirac point in the vicinity of $V_g = 0$ V.

II . Conclusions

Successful development of a method to electrically contact graphene (or any flat material) which has reduced contamination due to device fabrication process.

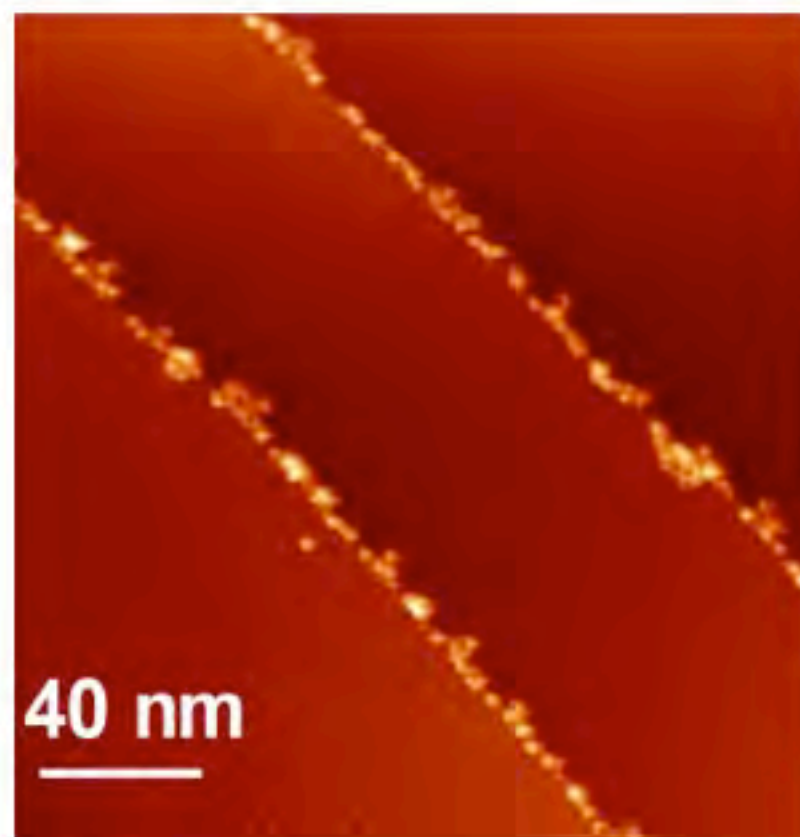
- Membrane' s alignment resolution $\sim 1\mu\text{m}$ ☒
- Membrane' s fabrication (FIB $\rightarrow$ easy and versatile) ☒
- Marked substrate facilitates alignment ☒

- Long FIB times for large patterns $\rightarrow$ increases the membrane' s fragility;
- Membrane planarity respect to the substrate;
- Large size graphene samples.

Compatibility with UHV technology

$\rightarrow$ *all-in-vacuum* device fabrication and characterization

Acknowledgement



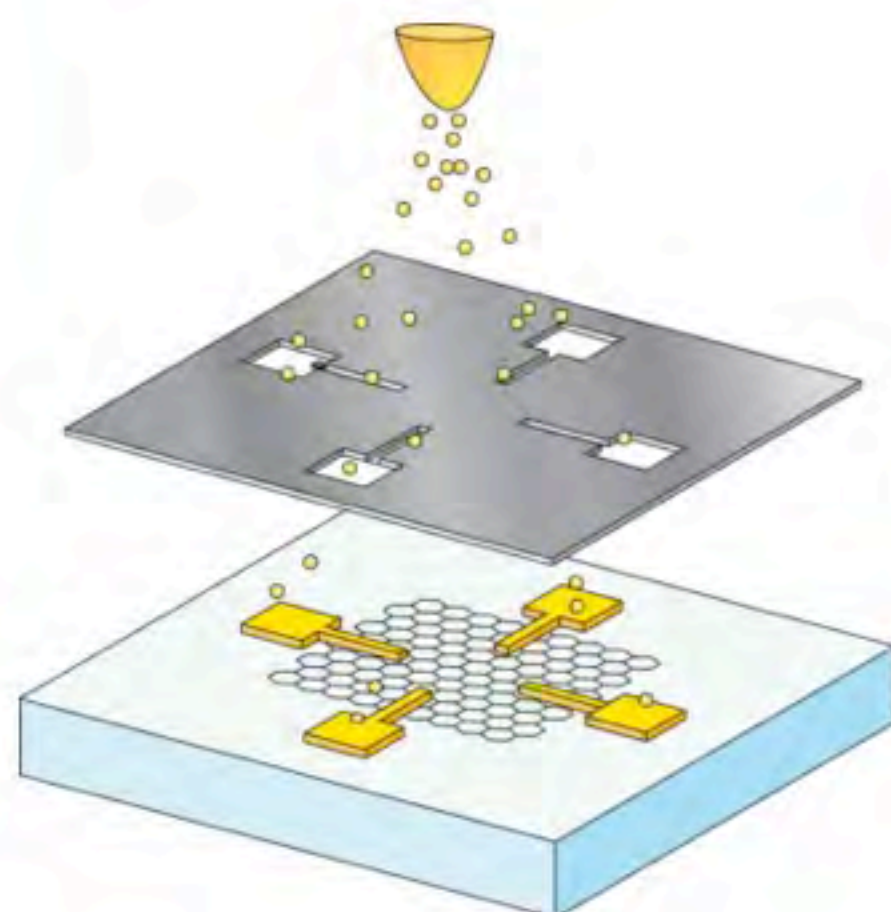
CVD of Graphene on Graphite @ SENSOR Università di Brescia

E. Cavaliere (Università Cattolica, Brescia)

L. Gavioli (Università Cattolica, Brescia & TASC Laboratories, Trieste)



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Stencil on graphene @ CEMES

E. Dujardin (CEMES, Toulouse)

V. Savu and J. Brugger (EPFL, Lausanne)

J. Grisolia (INSA, Toulouse)

